Material Specifications (27 °C hot side temperature)

<table>
<thead>
<tr>
<th>Material Specifications</th>
<th>Material Specifications (50 °C hot side temperature)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Vmax (V)</td>
<td>24.6</td>
</tr>
<tr>
<td>Imax (A)</td>
<td>11.3</td>
</tr>
<tr>
<td>Qmax (W)</td>
<td>172.0</td>
</tr>
<tr>
<td>DTmax (°C)</td>
<td>69</td>
</tr>
</tbody>
</table>

Module material specifications are nominal values based on the hot-side temperature indicated. Thermoelectric material parameter tolerance is +/-10%.

In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.

Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQ’s, and ordering information posted on our website before purchasing or using this product.

Optional Features and Notes:

- Add "P" to part number for sealing module with epoxy potting.

Performance graphs include thermal resistance of substrates.

NOTE: All specifications are subject to change without notice. © 2018 TE Technology, Inc.
Unpotted HP-199-1.4-0.8 at a hot-side temperature of 30 °C
Potted HP-199-1.4-0.8 at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice.
Unpotted HP-199-1.4-0.8 at a hot-side temperature of 50 °C
Potted HP-199-1.4-0.8 at a hot-side temperature of 50 °C
Unpotted HP-199-1.4-0.8 at a hot-side temperature of 70 °C

Note: All specifications subject to change without notice.
Potted HP-199-1.4-0.8 at a hot-side temperature of 70 °C